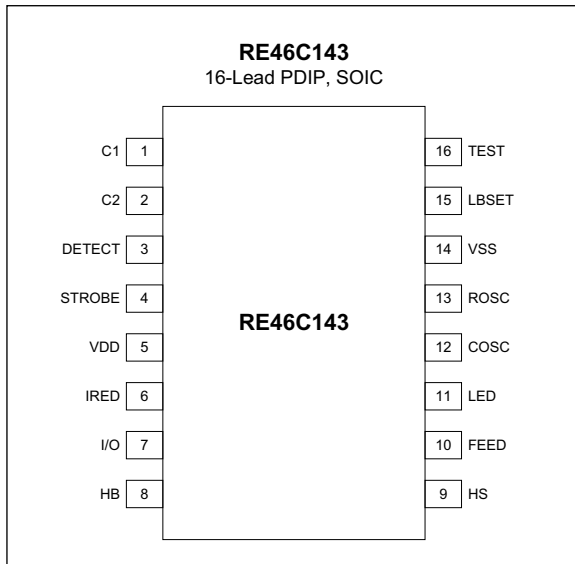


CMOS Photoelectric Smoke Detector ASIC with Interconnect

Features

- Internal Power On Reset (POR)
- Low Quiescent Current Consumption
- Electrostatic Discharge (ESD) Protection (HBM) on all Pins
- Interconnect up to 40 Detectors
- 75% Duty Cycle Horn Pattern
- Internal Low Battery and Chamber Test
- Available in RoHS Compliant Lead-Free Packaging
- Packaging:
 - 300 mil. 16-Lead PDIP
 - 3.90 mm 16-Lead SOIC
 - 7.50 mm 16-Lead SOIC
- Compatible with Motorola™ MC145010

Pin Configuration



General Description

RE46C143 is a low power CMOS photoelectric smoke detector integrated circuit (IC). Together with a few external components, this circuit provides all the required features for a photoelectric smoke detector.

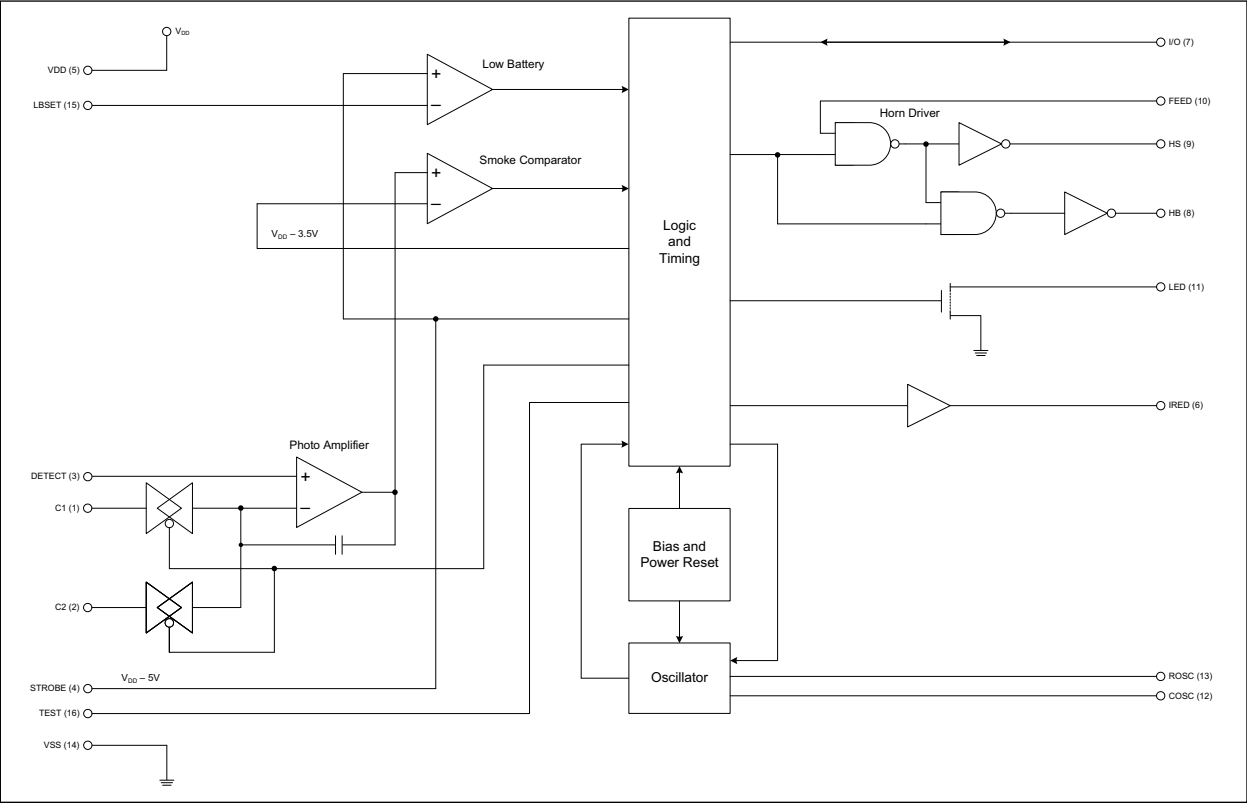
The design of RE46C143 includes a gain selectable photo amplifier used with an infrared emitter/detector pair. An internal oscillator strobes power to the smoke detector circuitry for 100 μ s every 8.1 seconds to keep standby current to a minimum. If smoke is sensed, the detection rate increases to verify the alarm condition. A high gain mode is available for push button chamber testing.

While in standby, RE46C143 checks for low battery condition and chamber integrity every 40 seconds. The alarm horn pattern uses a 75% duty cycle.

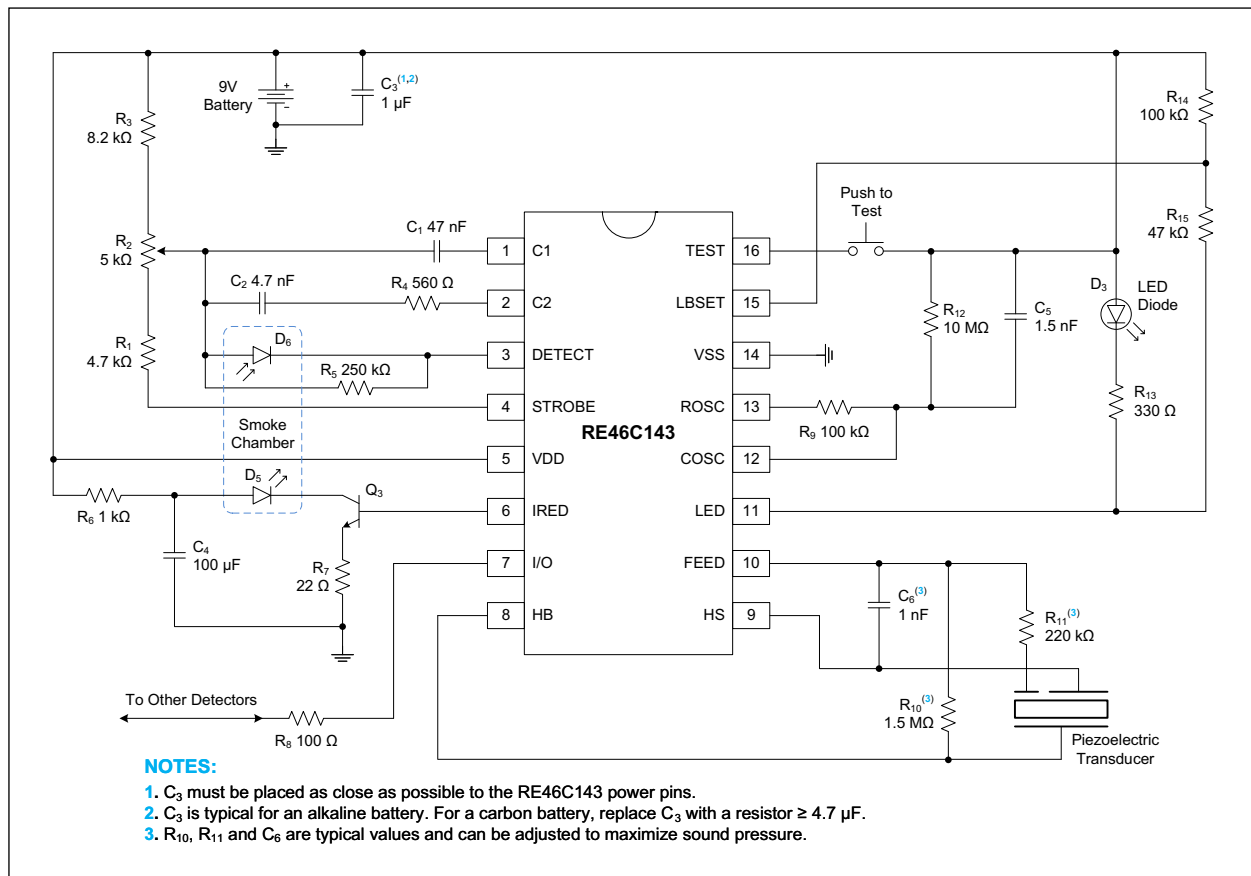
The interconnect pin (I/O) enables the connection of multiple detectors so that when one smoke detector alarms, all units sound together.

RE46C143

Functional Block Diagram



Typical Application



RE46C143

1.0 ELECTRICAL CHARACTERISTICS

1.1 Absolute Maximum Ratings†

Supply Voltage (V_{DD})	12.5V
Input Voltage Range except FEED and I/O (V_{IN})	-0.3V to $V_{DD} + 0.3V$
FEED Input Voltage Range (V_{INFD})	-10V to +22V
I/O Input Voltage Range (V_{IO1})	-0.3V to 17V
Input Current except FEED (I_{IN})	10 mA
Operating Temperature (T_A)	-25°C to +75°C
Storage Temperature (T_{STG})	-55°C to +125°C
Maximum Junction Temperature (T_J)	+150°C

† Notices:

- 1: Stresses above those listed under “Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these, or any other conditions above those indicated in the operation listings of this specification, is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.
- 2: Although this product uses CMOS technology with static protection, proper ESD prevention procedures must be used when handling this product. Damage can occur when exposed to extremely high static electric charge.

1.2 Electrical Specifications

TABLE 1-1: DC ELECTRICAL SPECIFICATIONS

DC Electrical Characteristics: Unless otherwise specified, all parameters apply at $T_A = -25^\circ\text{C}$ to $+75^\circ\text{C}$ and $V_{DD} = 9V$.							
Parameter	Symbol	Pin	Min.	Typical	Max.	Units	Conditions
Power Supply							
Supply Voltage	V_{DD}	VDD	6	—	12	V	Operating
Supply Current	I_{DD1}	VDD	—	4	6	μA	Typical Application, $\text{COSC} = V_{SS}$
	I_{DD2}	VDD	—	5.5	8	μA	Typical Application, $V_{DD} = 12V$, $\text{COSC} = V_{SS}$,
	I_{DD3}	VDD	—	—	2	mA	Typical Application, STROBE On, IRED Off, $V_{DD} = 12V$
	I_{DD4}	VDD	—	—	3	mA	Typical Application, STROBE On, IRED On, $V_{DD} = 12V$, Note 1
Input Voltage High	V_{IH1}	FEED	6.2	4.5	—	V	
	V_{IH2}	I/O	3.2	—	—	V	No Local Alarm, I/O as input
	V_{IH4}	TEST	8.5	—	—	V	

- Note**
- 1: Does not include Q3 emitter current.
 - 2: Not production tested.
 - 3: Typical values are for design information only and are not guaranteed by design.
 - 4: Limits over the specified temperature range are not production tested and are based on characterization data.

TABLE 1-1: DC ELECTRICAL SPECIFICATIONS (CONTINUED)

DC Electrical Characteristics: Unless otherwise specified, all parameters apply at $T_A = -25^{\circ}\text{C}$ to $+75^{\circ}\text{C}$ and $V_{DD} = 9\text{V}$.							
Parameter	Symbol	Pin	Min.	Typical	Max.	Units	Conditions
Power Supply (continued)							
Input Voltage Low	V_{IL1}	FEED	—	4.5	2.7	V	
	V_{IL2}	I/O	—	—	1.5	V	No Local Alarm, I/O as input
	V_{IL4}	TEST	—	—	7	V	
Input Leakage Low	I_{IL1}	C1, C2, DETECT	—	—	-100	nA	$V_{DD} = \text{COSC} = 12\text{V}$, STROBE Active
	I_{IL2}	COSC, LBSET	—	—	-100	nA	$V_{DD} = 12\text{V}$, $V_{IN} = V_{SS}$
	I_{IL3}	TEST	—	—	-1	μA	
	I_{LFD}	FEED	—	—	-50	μA	FEED = -10V
Input Leakage High	I_{IH1}	C1, C2	—	—	100	nA	$V_{DD} = 12\text{V}$, $V_{IN} = V_{DD}$, STROBE Active
	I_{IH2}	DETECT, COSC, LBSET	—	—	100	nA	$V_{DD} = 12\text{V}$, $V_{IN} = V_{DD}$
	I_{HFD}	FEED	—	—	50	μA	FEED = 22V
Input Pull Down Current	I_{PD1}	TEST	0.25	—	10	μA	$V_{IN} = V_{DD}$
	I_{PDIO1}	I/O	20	—	80	μA	
	I_{PDIO2}	I/O	—	—	140	μA	$V_{IN} = 17\text{V}$, $V_{DD} = 12\text{V}$
Output Off Leakage Low	I_{OZL1}	LED, ROSC	—	—	-1	μA	Output Off, Output = V_{SS}
Output Off Leakage High	I_{OZH1}	LED, ROSC	—	—	1	μA	Output Off, Output = V_{DD}
Output Voltage Low	V_{OL1}	HB, HS	—	—	1	V	$I_{OL} = 16\text{ mA}$, $V_{DD} = 6.5\text{V}$
	V_{OL2}	ROSC	—	0.5	—	V	$I_{OL} = 5\text{ mA}$, $V_{DD} = 6.5\text{V}$
	V_{OL3}	LED	—	—	0.6	V	$I_{OL} = 10\text{ mA}$, $V_{DD} = 6.5\text{V}$
Output Voltage High	V_{OH1}	HB, HS	5.5	—	—	V	$I_{OH} = -16\text{ mA}$, $V_{DD} = 6.5\text{V}$
Output Current	I_{IOH1}	I/O	-4	—	-16	mA	Alarm, $V_{IO} = 0\text{V}$ or $V_{IO} = V_{DD} - 2\text{V}$
	I_{IODMP}	I/O	5	—	—	mA	At the conclusion of Local Alarm or Test, $V_{IO} = 1\text{V}$

Note 1: Does not include Q3 emitter current.

2: Not production tested.

3: Typical values are for design information only and are not guaranteed by design.

4: Limits over the specified temperature range are not production tested and are based on characterization data.

RE46C143

TABLE 1-1: DC ELECTRICAL SPECIFICATIONS (CONTINUED)

DC Electrical Characteristics: Unless otherwise specified, all parameters apply at $T_A = -25^{\circ}\text{C}$ to $+75^{\circ}\text{C}$ and $V_{DD} = 9\text{V}$.							
Parameter	Symbol	Pin	Min.	Typical	Max.	Units	Conditions
Power Supply (continued)							
Low Battery Voltage	V_{LB}	VDD	6.9	7.2	7.5	V	$R_{14} = 100\text{ k}\Omega$, $R_{15} = 47\text{ k}\Omega$, $I_{LED} = 10\text{ mA}$
Offset Voltage	V_{STOFF}	STROBE	$V_{DD} - 0.1$	—	—	V	STROBE Off, $V_{DD} = 12\text{V}$, $I_{OUT} = -1\text{ }\mu\text{A}$
	V_{STON}	STROBE	$V_{DD} - 5.3$	$V_{DD} - 5$	$V_{DD} - 4.7$	V	STROBE On, $V_{DD} = 9\text{V}$, $I_{OUT} = 100\text{ to }500\text{ }\mu\text{A}$
	$V_{IREDOFF}$	IREDD	—	—	0.1	V	IREDD Off, $V_{DD} = 12\text{V}$, $I_{OUT} = 1\text{ }\mu\text{A}$
	V_{IREDON}	IREDD	2.25	3.1	3.75	V	IREDD On, $V_{DD} = 9\text{V}$, $I_{OUT} = 0\text{ to }-6\text{ mA}$, $T_A = +25^{\circ}\text{C}$
Common Mode Voltage	V_{CM1}	C1, C2, DETECT	0.5	—	$V_{DD} - 2$	V	Local Smoke, Push to Test or Chamber Test, Note 2
Smoke Comparator Reference	V_{REF}	—	$V_{DD} - 3.85$	—	$V_{DD} - 3.15$	V	Internal Reference
Temperature Coefficient	TC_{ST}	STROBE	—	0.01	—	%/ $^{\circ}\text{C}$	$V_{DD} = 6\text{V to }12\text{V}$, STROBE Output Voltage
	TC_{IREDD}	LED	—	0.3	—	%/ $^{\circ}\text{C}$	$V_{DD} = 6\text{V to }12\text{V}$, IREDD Output Voltage
Line Regulation	ΔV_{STON}	STROBE, VDD	—	-50	—	dB	Active, $V_{DD} = 6\text{V to }12\text{V}$
	ΔV_{IREDON}	VDD, IREDD	—	-30	—	dB	

Note 1: Does not include Q3 emitter current.

2: Not production tested.

3: Typical values are for design information only and are not guaranteed by design.

4: Limits over the specified temperature range are not production tested and are based on characterization data.

TABLE 1-2: AC ELECTRICAL SPECIFICATIONS

AC Electrical Characteristics: Unless otherwise specified, all parameters apply at $T_A = -25^{\circ}\text{C}$ to $+75^{\circ}\text{C}$, $V_{DD} = 9\text{V}$, $V_{SS} = 0\text{V}$, $R_9 = 100\text{ k}\Omega$, $R_{12} = 10\text{ M}\Omega$ and $C_5 = 1.5\text{ nF}$.							
Parameter	Symbol	Pin	Min.	Typical	Max.	Units	Conditions
Oscillator Time Base							
Oscillator Period	t_{POSC}	COSC	9.4	10.5	11.5	ms	No Alarm Condition, Note 1
STROBE, LED and IRED Indication							
STROBE and LED On Time	t_{ON1}	STROBE, LED	9.4	10.5	11.5	ms	Operating
LED Period	t_{PLED1}	LED	38	43	47	s	Standby, No Alarm
	t_{PLED2}	LED	0.6	0.67	0.74	s	Local Alarm Condition
	t_{PLED4}	LED	LED IS OFF				Remote Alarm Only
STROBE and IRED Pulse Period	t_{PER1}	STROBE, IRED	9.7	10.5	11.8	s	Standby, No Alarm
	t_{PER1A}	STROBE, IRED	2.42	2.7	2.96	s	Standby, After 1 Valid Smoke Sample
	t_{PER1B}	STROBE, IRED	1.21	1.33	1.47	s	Standby, After 2 Consecutive Valid Smoke Samples
	t_{PER2}	STROBE, IRED	1.21	1.33	1.47	s	In Local Alarm (Requires 3 Consecutive Valid Smoke Samples)
	t_{PER3}	STROBE, IRED	9.7	10.5	11.8	s	In Remote Alarm
	t_{PER4}	STROBE, IRED	—	0.336	—	s	Push Button Test
	t_{PER5}	STROBE, IRED	39	—	47	s	Chamber Test or Low Battery Test, No Alarms
IRED On Time	t_{ON2}	IRED	94	104	115	μs	Operating, Note 1
Horn Indication							
Horn On Time	t_{HON1}	HB, HS	227	252	277	ms	Operating, Alarm Condition, Note 2
	t_{HON2}	HB, HS	9.5	10.5	11.5	ms	Low Battery or Failed Smoke Chamber Test, No Alarm
Horn Off Time	t_{HOFF1}	HB, HS	76	84	92	ms	Operating, Alarm Condition, Note 2
	t_{HOFF3}	HB, HS	39	43	47	s	Low Battery or Failed Smoke Chamber Test, No Alarm
I/O Charge Dump Duration	t_{IODMP}	I/O	0.91	—	1.46	s	At the conclusion of Local Alarm or Test Alarm
I/O Delay	t_{IODLY1}	I/O	—	0	—	s	From the start of Local Alarm to I/O Active

Note 1: t_{POSC} and t_{ON2} are 100% production tested. All other timings are guaranteed by functional design.

2: See timing diagram for Temporal Horn Pattern in [Figure 3-1](#).

3: Typical values are for design information only and are not guaranteed by design.

4: Limits over the specified temperature range are not production tested and are based on characterization data.

RE46C143

TABLE 1-2: AC ELECTRICAL SPECIFICATIONS (CONTINUED)

AC Electrical Characteristics: Unless otherwise specified, all parameters apply at $T_A = -25^{\circ}\text{C}$ to $+75^{\circ}\text{C}$, $V_{DD} = 9\text{V}$, $V_{SS} = 0\text{V}$, $R_9 = 100\text{ k}\Omega$, $R_{12} = 10\text{ M}\Omega$ and $C_5 = 1.5\text{ nF}$.							
Parameter	Symbol	Pin	Min.	Typical	Max.	Units	Conditions
Horn Indication (continued)							
I/O Filter	t_{IOFILT}	I/O	—	—	0.6	s	I/O pulse width guaranteed to be filtered. I/O as input, No Local Alarm
Remote Alarm Delay	t_{IODLY2}	I/O	0.75	—	1.65	s	No Local Alarm, from I/O active to Horn Active

- Note 1:** t_{POSC} and t_{ON2} are 100% production tested. All other timings are guaranteed by functional design.
- 2:** See timing diagram for Temporal Horn Pattern in [Figure 3-1](#).
- 3:** Typical values are for design information only and are not guaranteed by design.
- 4:** Limits over the specified temperature range are not production tested and are based on characterization data.

TABLE 1-3: TEMPERATURE CHARACTERISTICS

DC Electrical Characteristics: Unless otherwise specified, all parameters apply at $V_{DD} = 9\text{V}$ and $V_{SS} = 0\text{V}$ (typical application).						
Parameter	Symbol	Min.	Typical	Max.	Units	Conditions
Temperature Ranges						
Specified Temperature Range	T_A	-25	—	+75	$^{\circ}\text{C}$	
Operating Temperature Range	T_{OP}	-25	—	+75	$^{\circ}\text{C}$	
Storage Temperature Range	T_{STG}	-55	—	+125	$^{\circ}\text{C}$	
Thermal Package Resistances						
Thermal Resistance, 16-Lead PDIP	θ_{JA}	—	70	—	$^{\circ}\text{C/W}$	
Thermal Resistance, 16-Lead SOIC	θ_{JA}	—	86.1	—	$^{\circ}\text{C/W}$	

2.0 PIN DESCRIPTION

Table 2-1 describes the pins of RE46C143.

TABLE 2-1: RE46C143 PIN FUNCTION

Pin Number	Symbol	Description
1	C1	Connect a capacitor to this pin to set the photo amplifier gain (high) for the push button and chamber sensitivity tests. The size of the capacitor depends on the chamber background reflections. $A = 1 + (C_1/10)$, where C_1 is measured in pF. The photo amplifier gain must be less than 10,000.
2	C2	Connect a capacitor to this pin to set the photo amplifier gain (normal) during standby. The size of the capacitor depends on the required smoke sensitivity. $A = 1 + (C_2/10)$, where C_2 is measured in pF.
3	DETECT	Positive input of the photo amplifier. This pin usually connects to the cathode of an external photo diode operated at zero bias.
4	STROBE	Regulated output voltage of $V_{DD} - 5V$. The voltage is active during smoke tests. This pin is the negative input of the photo amplifier circuitry.
5	VDD	Connects to the positive power supply.
6	IREDD	IREDD Driver Pin. It provides a regulated pulsed output voltage pre-driver for the infrared emitter. This pin usually drives the base of an NPN transistor.
7	I/O	Interconnect Pin. Use this bidirectional pin to connect multiple detectors in a single system. If one unit goes into alarm, the I/O pin is driven high causing all the interconnected detectors to alarm. This pin has an internal pull-down device.
8	HB	Horn Brass, Inverted Output. This pin connects to the metal electrode of a piezoelectric transducer.
9	HS	Horn Silver Output. This pin is a complementary output to the HB pin and connects to the ceramic electrode of the piezoelectric transducer.
10	FEED	Feedback Pin. It connects to the feedback electrode through a current limiting resistor. If not used, ensure the FEED pin connects to V_{DD} or V_{SS} .
11	LED	LED Driver Pin. Open-drain NMOS output used to drive a visible LED.
12	COSC	Connect a capacitor with a parallel resistor to this pin to set the internal clock low time. This value is approximately the clock period.
13	ROSC	Connect a capacitor between this pin and the COSC pin to set the internal clock high time. This also sets the IRED pulse width (100 to 200 μs).
14	VSS	This pin connects to the negative power supply.
15	LBSET	This pin connects to a V_{DD} reference voltage to set the low battery warning voltage.
16	TEST	Use this pin to enter two Test modes. It has an internal pull-down device.

RE46C143

3.0 DEVICE DESCRIPTION

3.1 Introduction

RE46C143 is a low power CMOS photoelectric smoke detector integrated circuit (IC). Together with a few external components, this circuit provides all the required features for an ionization type smoke detector.

Note: All timing references are nominal values. Refer to [Table 1-1](#) and [Table 1-2](#) for limits.

3.2 Internal Timing

With external components connected to the ROSC and COSC pins as indicated in the [Typical Application](#) diagram, the internal oscillator period is nominally $t_{POSC} = 10$ ms. Usually, the analog circuitry is powered down to minimize standby current (4 μ A at 9V, typical value).

The detection circuitry (normal gain) is powered up for 10 ms every 10 seconds. Before this 10 ms period ends, the IRED pulse activates for 100 μ s. At the end of this 10 ms period, but not after, the photo amplifier is compared to an internal reference to determine its status and then latched. If a smoke condition is detected, the time until the next detection decreases and additional checks are made. Three consecutive smoke detections cause the RE46C143 device to alarm and its horn circuit and interconnect activate.

Every 40 seconds, the status of the battery voltage is checked and latched at the end of the LED pulse.

Every 10 seconds, the photo chamber samples using normal gain (capacitor C_2). Additionally, once every 40 seconds, the photo chamber activates using the high gain mode (capacitor C_1) and RE46C143 checks the photo chamber by amplifying background reflections. If the low battery check or the photo chamber test fails, the horn chirps for 10 ms once every 40 seconds.

The oscillator period (t_{POSC}) is determined by the values of the R_9 and R_{12} resistors and the C_5 capacitor, as shown in the [Typical Application](#) diagram:

$R_9 = 100$ k Ω , $R_{12} = 10$ M Ω and $C_5 = 1.5$ nF

The oscillator period is calculated using [Equation 3-1](#).

EQUATION 3-1:

$$\begin{aligned} t_{POSC} &= t_R + t_F \\ t_R &= 0.6931 \times R_{12} \times C_5 \\ t_F &= 0.6931 \times R_9 \times C_5 \end{aligned}$$

Where:

t_{POSC} = Oscillator Period (ms)

3.3 Smoke Detection Circuitry

A comparator takes the value of the photo amplifier output and compares it to an internal reference voltage. If RE46C143 detects three consecutive smoke conditions, the device enters local alarm and the horn activates. During a local alarm, the C_2 gain is internally increased by $\sim 10\%$ to provide alarm hysteresis.

3.4 Push-to-Test

When one internal clock cycle passes after the TEST pin activates (V_{IH}), the smoke detection rate increases from once every 10 seconds to once every 330 ms. In Push-to-Test mode, RE46C143 selects the high gain capacitor (C_1) and then uses background reflections to simulate a smoke condition. If RE46C143 detects three consecutive smoke conditions, the device enters local alarm.

When one internal clock cycle passes after the TEST pin deactivates (V_{IL}), RE46C143 selects the normal gain capacitor (C_2). The detection rate continues at once every 330 ms until RE46C143 detects three consecutive no-smoke conditions. After this, the device returns to standby timing.

3.5 LED Pulse

The LED pulses on for 10 ms every 40 seconds while in standby.

During a local alarm or push-to-test alarm, the LED pulses on every 0.5 seconds. However, during a remote alarm, the LED does not activate.

3.6 Interconnect

Use the I/O pin to interconnect multiple detectors into a single system. If one unit enters local alarm, the I/O pin is driven high through a constant current source and all other connected detectors enter remote alarm and sound together.

Short-circuiting the I/O pin to ground does not cause excessive current. The I/O pin is ignored when the device is in local alarm.

The I/O pin includes a NMOS discharge device that activates for one second after any local alarm ends. This NMOS device quickly discharges any capacitors associated with the interconnect line.

When RE46C143 detects a remote active high signal, the device enters remote alarm and the horn activates. The internal protection circuitry allow the signaling unit to have a higher supply voltage than the signaled units without drawing excessive current.

The interconnect input (I/O pin) has a 500 ms nominal digital filter. This allows to interconnect other types of alarm devices, such as carbon monoxide detectors, that have a pulsed interconnect signal.

3.7 Low Battery and Chamber Test

In standby, an internal voltage reference is compared to the voltage divided V_{DD} power supply. Low battery status is latched when the LED pulse ends. The horn chirps for 10 ms every 40 seconds until the low battery condition is no longer present.

In standby, a photo chamber test is also performed every 40 seconds by switching from the normal gain capacitor C_2 to the high gain capacitor C_1 . RE46C143 then tries to sense the background reflections of the photo chamber. Two consecutive failed chamber tests trigger the horn to chirp for 10 ms every 40 seconds.

The low battery chirp occurs immediately before the LED pulse, while the failed chamber test chirp sounds 20 seconds later.

The low battery alarm threshold is $\approx 5 + 5 \times R_{15}/R_{14}$, where R_{14} and R_{15} are in the same smoke detector.

Note: Low battery and chamber tests are not performed when RE46C143 is in local or remote alarm.

3.8 Diagnostic Mode

Besides the usual function of the TEST pin, a special Diagnostic mode is available for the calibration and testing of the smoke detector.

To enable Diagnostic mode, pull the TEST pin below V_{SS} and source $\sim 300 \mu A$ out of the pin for one clock cycle.

In Diagnostic mode, some pin functions are redefined, as shown in [Table 3-1](#). Additionally, in this mode, the strobe is always active and the IRED pulses at a clock rate of 10 ms (nominal value).

TABLE 3-1: DIAGNOSTIC MODE – REDEFINED PIN FUNCTIONS

Pin Name	Pin Number	Redefined Function
I/O	7	Disabled as output. Pulling the I/O pin high directs the photo amplifier output to the C1 or C2 pin, depending if the LBSET pin is pulled high or low. Amplification occurs while the IRED is active.
LBSET	15	If the I/O pin is pulled high, the LBSET pin controls what the gain capacitor is used. If the LBSET pin is pulled low, then the normal gain capacitor (C_2) is selected and the photo amplifier output is directed to the C1 pin. If the LBSET pin is pulled high, then the high gain capacitor (C_1) is selected the photo amplifier output is directed to the C2 pin.
FEED	10	If the LBSET pin is pulled low, then pulling the FEED pin high enables hysteresis, leading to a nominal 10% gain increase in normal gain mode.
COSC	12	The COSC pin can be driven by an external clock.
HB	8	The HB pin becomes output for the smoke integrator. A high level output indicates that an alarm condition was detected.
LED	11	The LED pin is used as a low battery indicator. When V_{DD} is above the low battery threshold, the open-drain NMOS turns off. When V_{DD} falls below the threshold, the NMOS turns on.

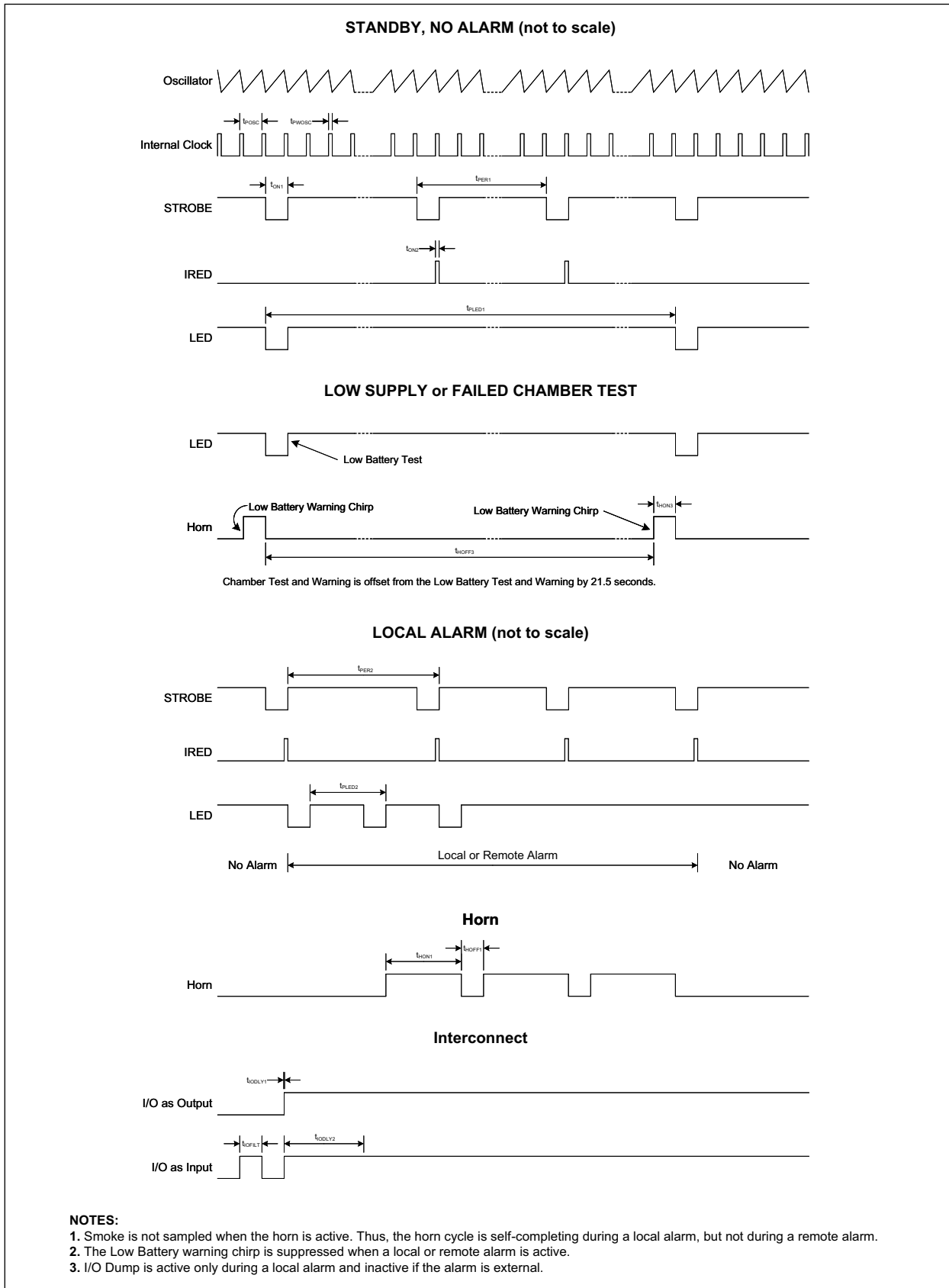


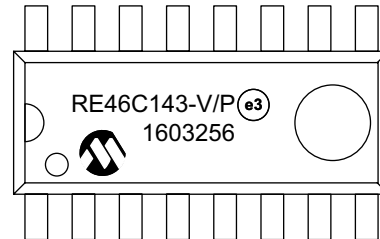
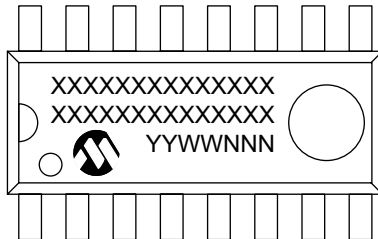
FIGURE 3-1: RE46C143 Timing Diagrams.

4.0 PACKAGING INFORMATION

4.1 Package Marking Information

RE46C143
16-Lead PDIP, 300 mil. Body

Example:

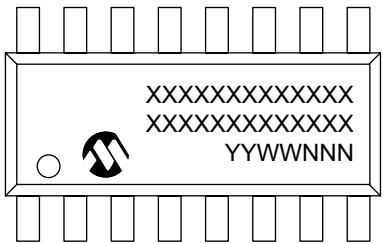


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

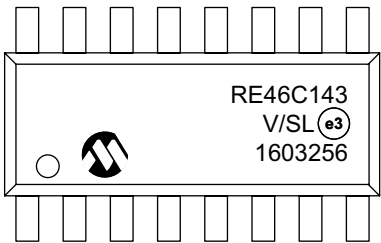
Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

RE46C143

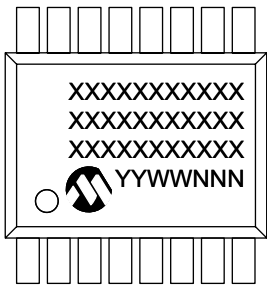
RE46C143
16-Lead SOIC, 3.90 mm Body



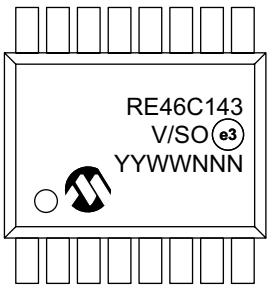
Example:



RE46C143
16-Lead SOIC, 7.50 mm Body



Example:

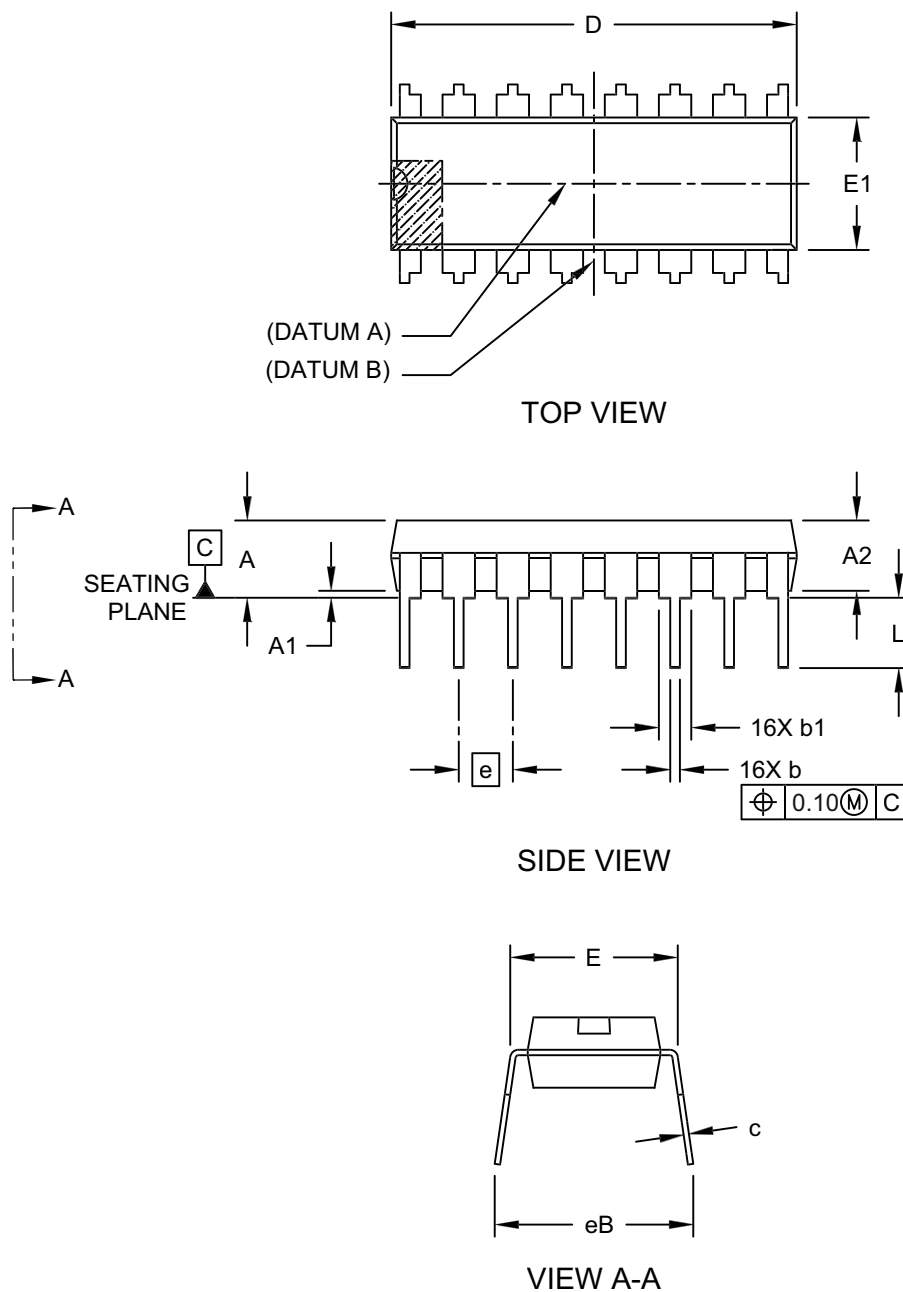


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.
Note:	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.	

4.2 Package Drawings

16-Lead Plastic Dual In-Line (P) - 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

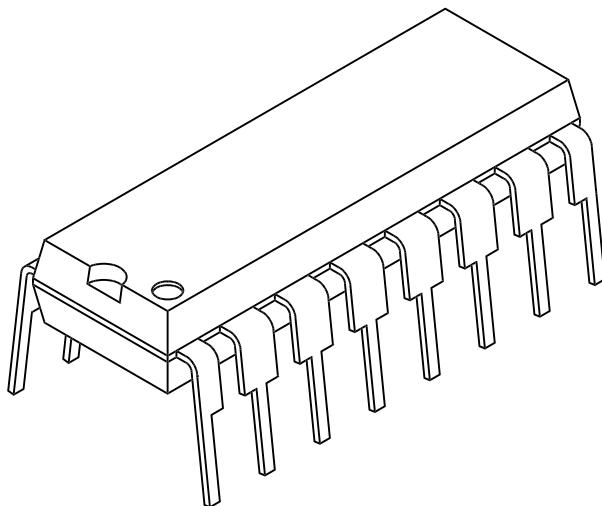


Microchip Technology Drawing C04-00017 Rev C (P) Sheet 1 of 2

RE46C143

16-Lead Plastic Dual In-Line (P) - 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	INCHES		
Dimension Limits			MIN	NOM	MAX
Number of Pins	N		16		
Pitch	e		.100 BSC		
Top to Seating Plane	A		-	-	.210
Molded Package Thickness	A2		.115	.130	.195
Base to Seating Plane	A1		.015	-	-
Shoulder to Shoulder Width	E		.290	.310	.325
Molded Package Width	E1		.240	.250	.280
Overall Length	D		.735	.750	.775
Tip to Seating Plane	L		.115	.130	.150
Lead Thickness	c		.008	.010	.015
Upper Lead Width	b1		.045	.060	.070
Lower Lead Width	b		.014	.018	.022
Overall Row Spacing	§	eB	-	-	.430

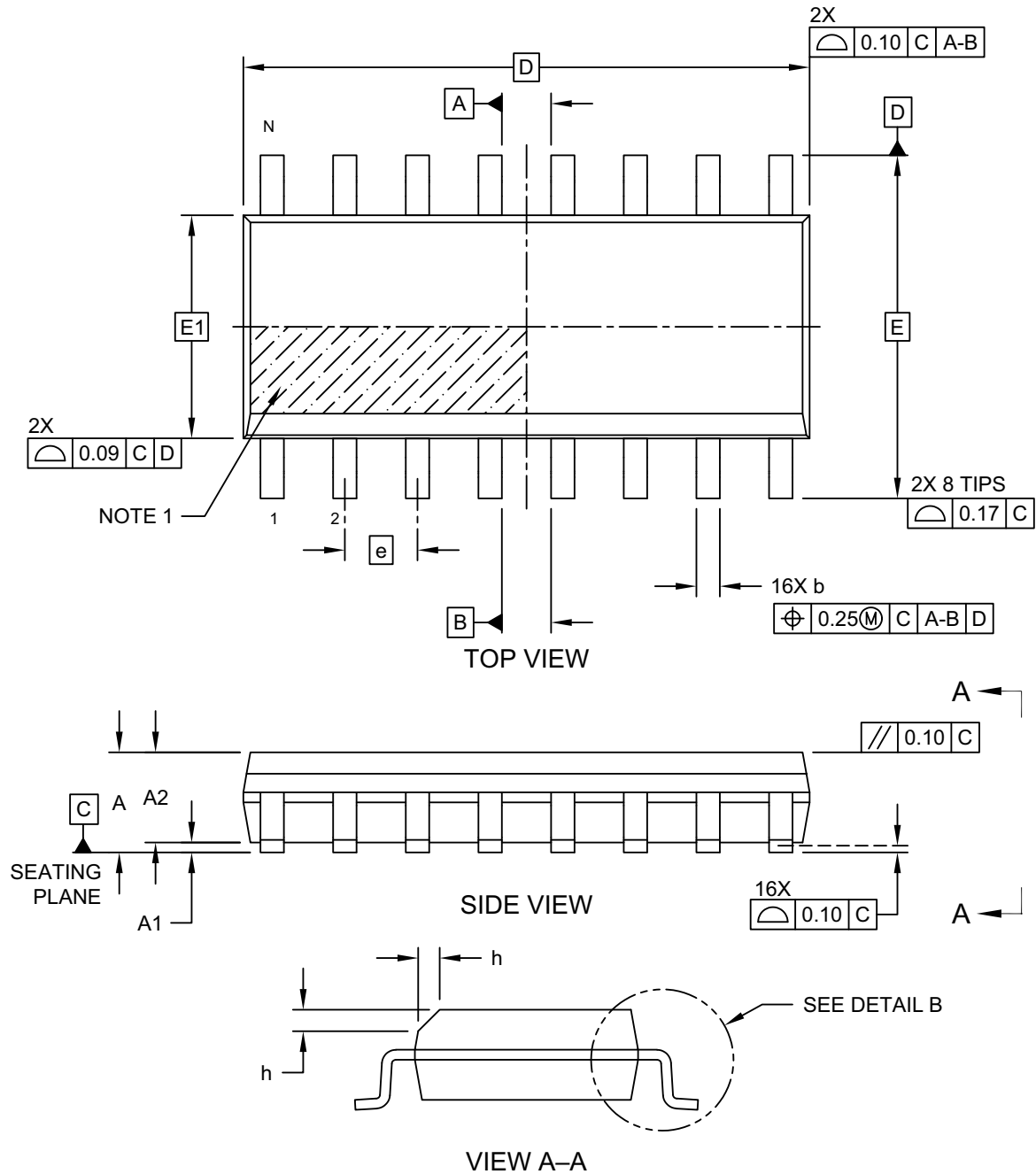
Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
 2. § Significant Characteristic
 3. Dimensions D and E do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" per side.
 4. Dimensioning and tolerancing per ASME Y14.5M
- BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-00017 Rev C (P) Sheet 2 of 2

16-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

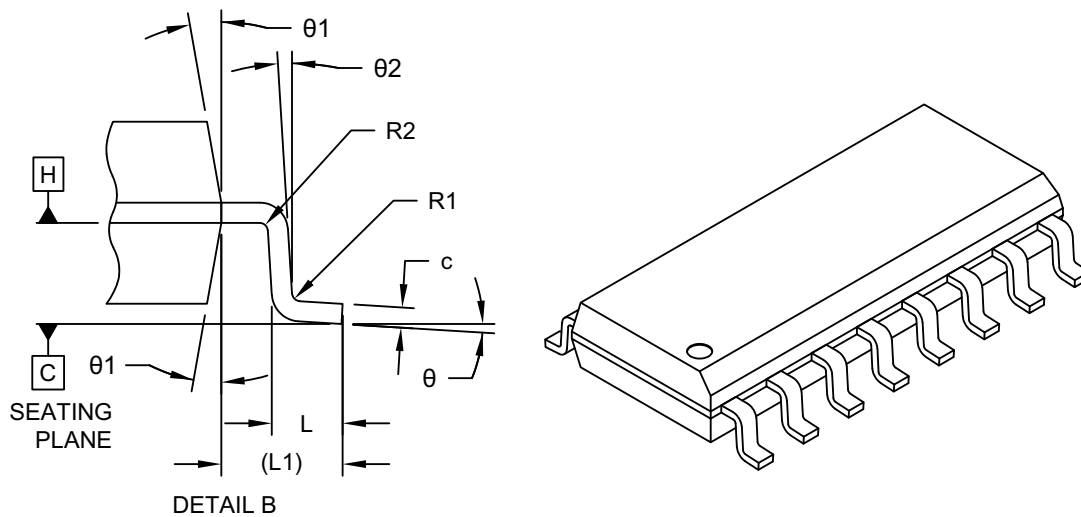
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-108-SL Rev E Sheet 1 of 2

16-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Terminals	N	16		
Pitch	e	1.27 BSC		
Overall Height	A	-	-	1.75
Standoff §	A1	0.10	-	0.25
Molded Package Thickness	A2	1.25	-	-
Overall Length	D	9.90 BSC		
Overall Width	E	6.00 BSC		
Molded Package Width	E1	3.90 BSC		
Terminal Width	b	0.31	-	0.51
Terminal Thickness	c	0.10	-	0.25
Corner Chamfer	h	0.25	-	0.50
Terminal Length	L	0.40	-	1.27
Footprint	L1	1.04 REF		
Lead Bend Radius	R1	0.07	-	-
Lead Bend Radius	R2	0.07	-	-
Foot Angle	θ	0°	-	8°
Mold Draft Angle	θ1	0°	-	15°
Lead Angle	θ2	0°	-	-

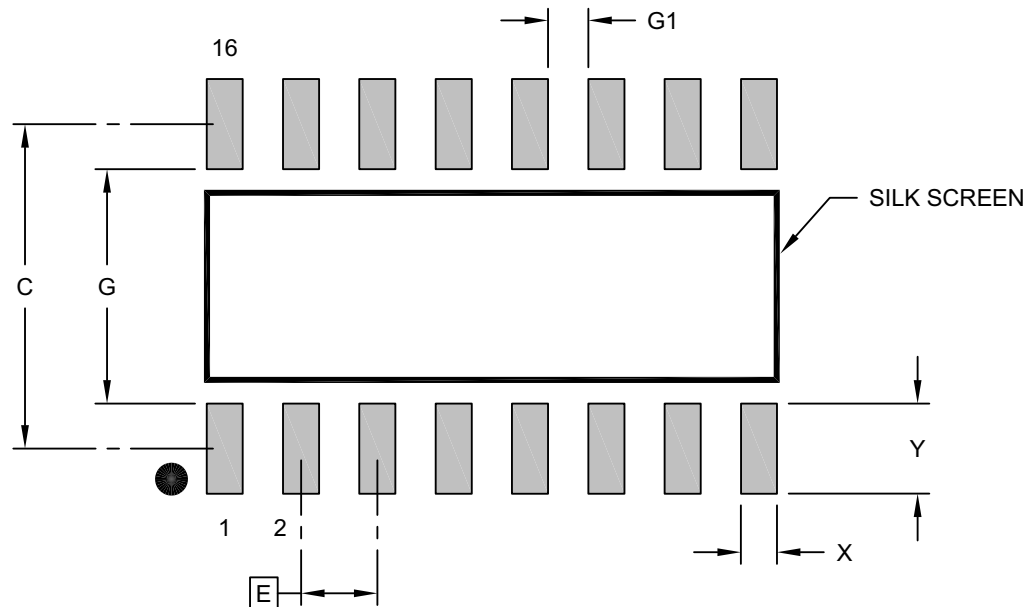
Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.
- Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-108-SL Rev E Sheet 2 of 2

16-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		5.40	
Contact Pad Width (X16)	X			0.60
Contact Pad Length (X16)	Y			1.50
Contact Pad to Contact Pad (X8)	G	3.90		
Contact Pad to Contact Pad (X14)	G1	0.67		

Notes:

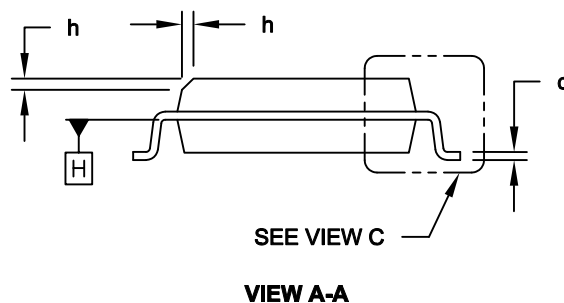
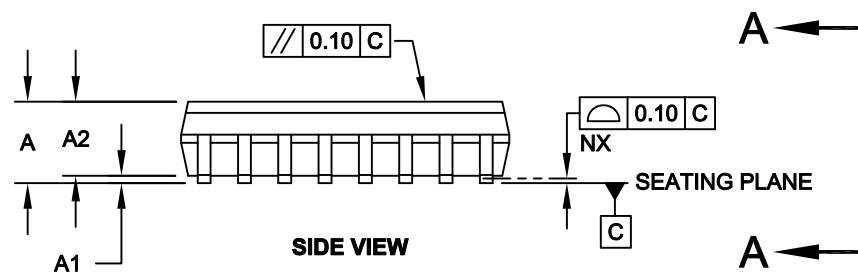
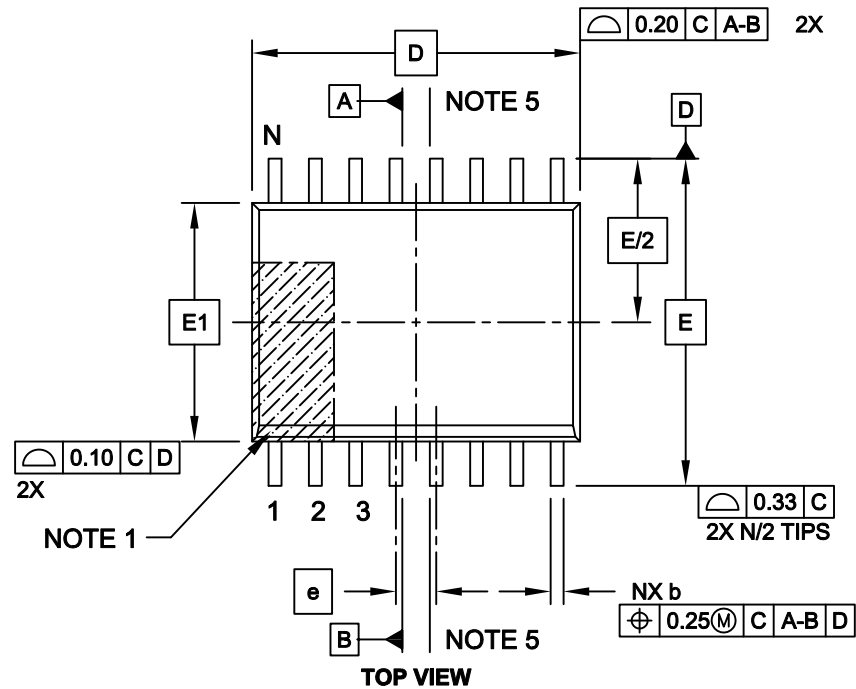
1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2108-SL Rev E

RE46C143

16-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

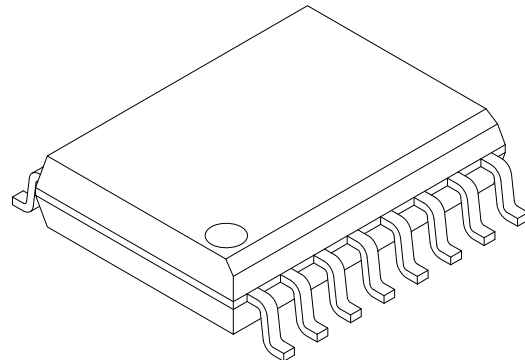
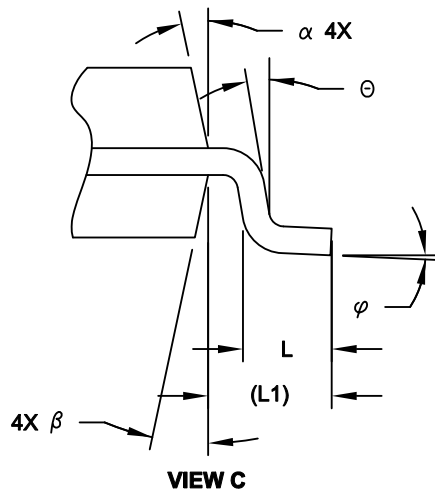
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-102C Sheet 1 of 2

16-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	16		
Pitch	e	1.27 BSC		
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E	10.30 BSC		
Molded Package Width	E1	7.50 BSC		
Overall Length	D	10.30 BSC		
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1	1.40 REF		
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.20	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

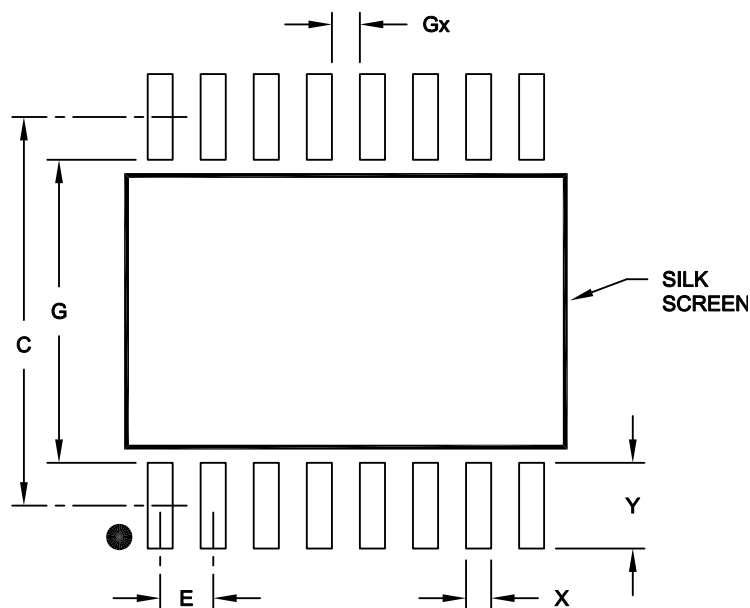
Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.
- Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-102C Sheet 2 of 2

16-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.30	
Contact Pad Width	X			0.60
Contact Pad Length	Y			2.05
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2102A

APPENDIX A: REVISION HISTORY

Revision C (October 2025)

- Removed mentions of Underwriters Laboratory Specifications UL217 and UL268.
- Updated [Functional Block Diagram](#) and [Typical Application](#).
- Updated [Figure 3-1](#).
- Added [Section 2.0, "Pin Description"](#).
- Updated [Section 3.0, "Device Description"](#).
- Added [Section 4.0, "Packaging Information"](#).
- Added [Product Identification System](#) section.

Revision B (June 2009)

- Undocumented changes.

Revision A (May 2009)

- Initial release of this document.

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	XX	XX	X	X
Device	Package	Number of Pins	Tape and Reel Option⁽¹⁾	Lead Free
Device: RE46C143 = CMOS Photoelectric Smoke Detector ASIC				
Package: E = Plastic Dual In-line (P), 300 mil. Body (PDIP) S = Plastic Small Outline (SL), 3.90 mm Body (SOIC) SW = Plastic Small Outline (SO), 7.50 mm Body (SOIC)				
Number of Pins: 16 = 16-Lead				
Tape and Reel Option: Blank = Standard Packaging (Tube) T = Tape and Reel ⁽¹⁾				
Lead Free: F = Lead (Pb) Free Packaging				
Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.				
Examples:				
a) RE46C143E16F = CMOS Photoelectric Smoke Detector ASIC, Plastic Dual In-Line, 300 mil. Body PDIP, 16-Lead, Lead (Pb) Free				
b) RE46C143S16F = CMOS Photoelectric Smoke Detector ASIC, Plastic Small Outline, 3.90 mm Body SOIC, 16-Lead, Lead (Pb) Free				
c) RE46C143S16TF = CMOS Photoelectric Smoke Detector ASIC, Plastic Small Outline, 3.90 mm Body SOIC, 16-Lead, Tape and Reel, Lead (Pb) Free				
d) RE46C143SW16F = CMOS Photoelectric Smoke Detector ASIC, Plastic Small Outline, 7.50 mm Body SOIC, 16-Lead, Lead (Pb) Free				
e) RE46C143SW16TF = CMOS Photoelectric Smoke Detector ASIC, Plastic Small Outline, 7.50 mm Body SOIC, 16-Lead, Tape and Reel, Lead (Pb) Free				

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